

Chip Bead Array

Type: **EXC28B**



■ Features

- Space saving
- SSOP package(0.5 mm pitch) compatibility
- Small size and lightweight

Type: **EXC28BB**

- For high speed signal (over 50 MHz)
- Excellent cross talk characteristics (100 MHz:<-25 dB)

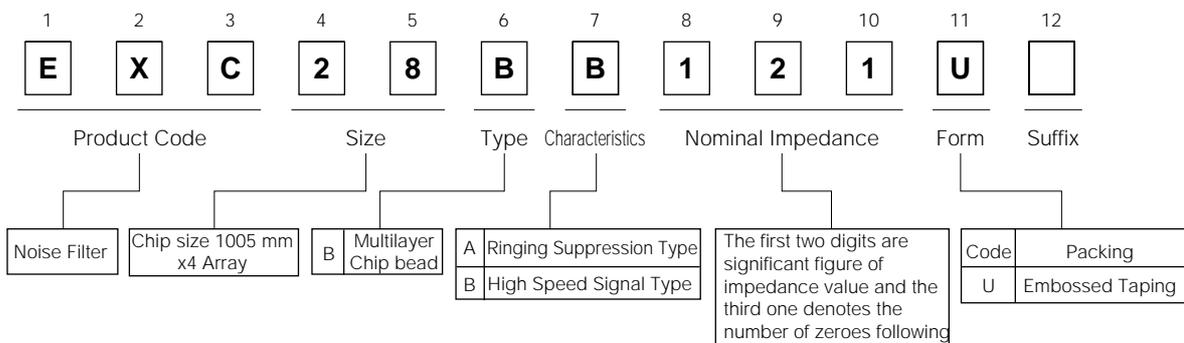
Type: **EXC28BA**

- Reduces waveform ringing noise
- Excellent cross talk characteristics (100 MHz:<-30 dB)

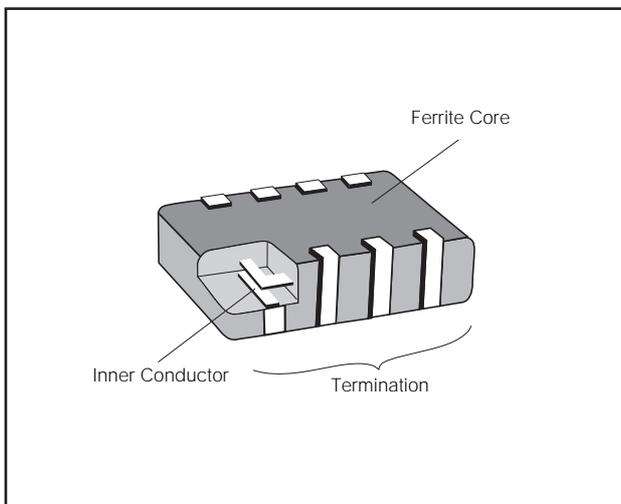
■ Recommended Applications

- Small digital equipment such as Personal Computers, Printers, HDD, DVD and CD ROMs, LCDs
- Digital audio and video equipment such as DSC, DVC, CD Players, DVD Players, MD Players
- Electronic musical instruments and other small digital equipment

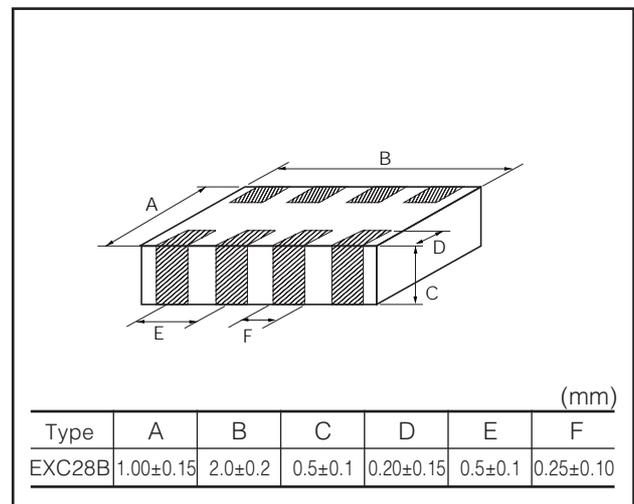
■ Explanation of Part Numbers



■ Construction



■ Dimensions in mm (not to scale)

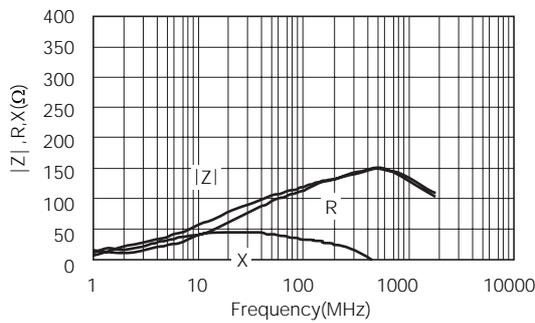


■ Ratings

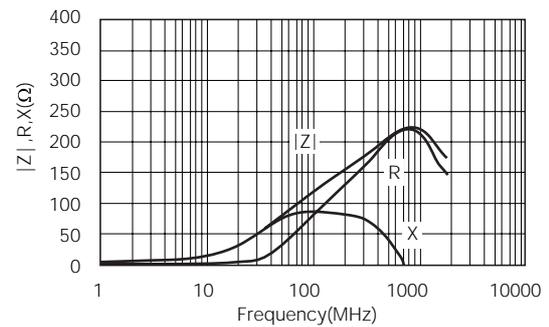
Type	Part No.	Impedance		Rated Current (mA DC)	DC Resistance (Ω) max.
		(Ω) at 100 MHz	tol.(%)		
BA	EXC28BA121U	120	±25	100	0.5
	EXC28BA221U	220			0.7
BB	EXC28BB121U	120			0.5
	EXC28BB221U	220			0.7

■ Impedance Characteristics (Reference Data) Measured by HP4291A

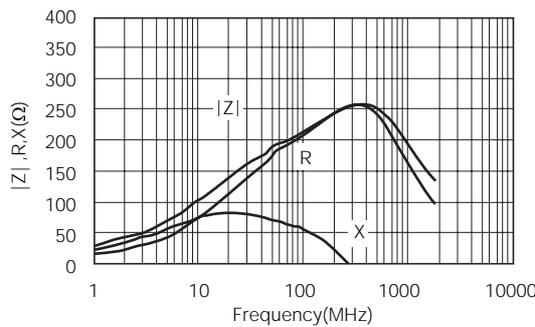
● EXC28BA121 (2010)



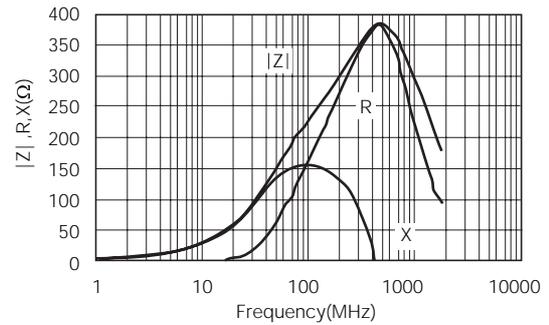
● EXC28BB121 (2010)



● EXC28BA221 (2010)

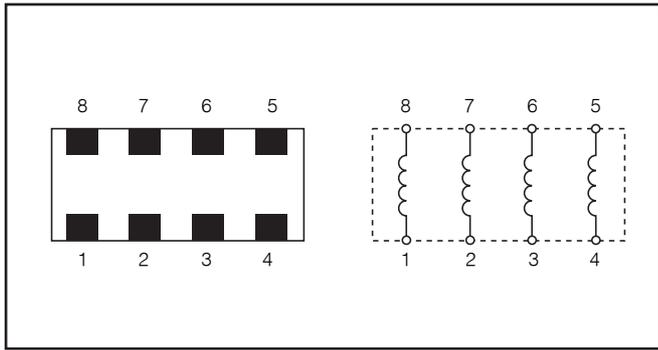


● EXC28BB221 (2010)



|Z| : Impedance R : Resistance X : Reactance

■ Circuit Configuration

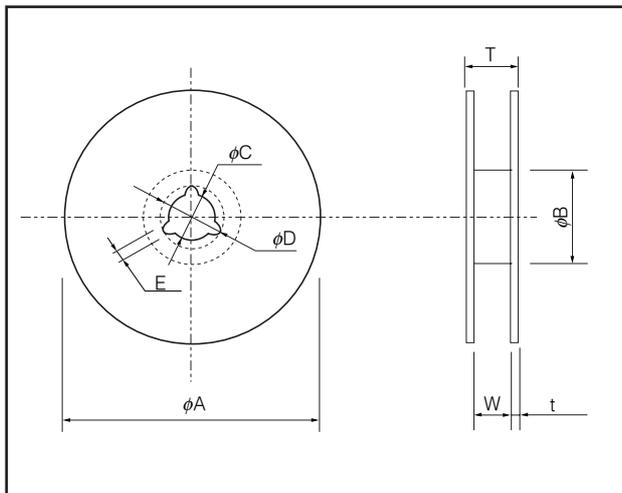


■ Packaging Specifications

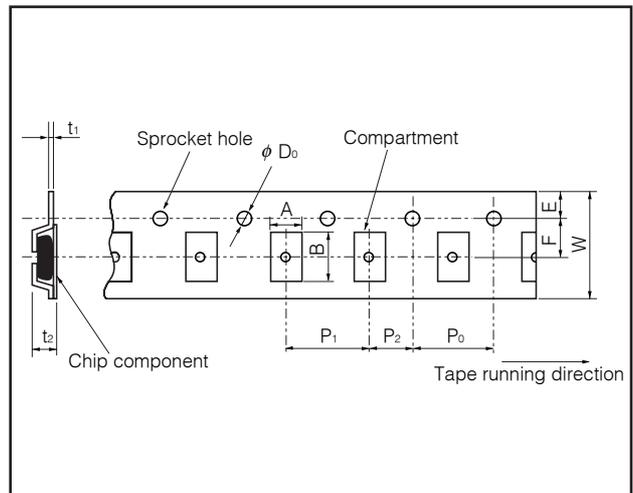
● Standard Quantity

Part Number	Embossed Taping	Weight (mg/pc.) Reference Data
EXC28B□□□□U	5000 pcs./reel	5.2

● Standard Reel Dimensions in mm



● Embossed Carrier Dimensions in mm (not to scale)



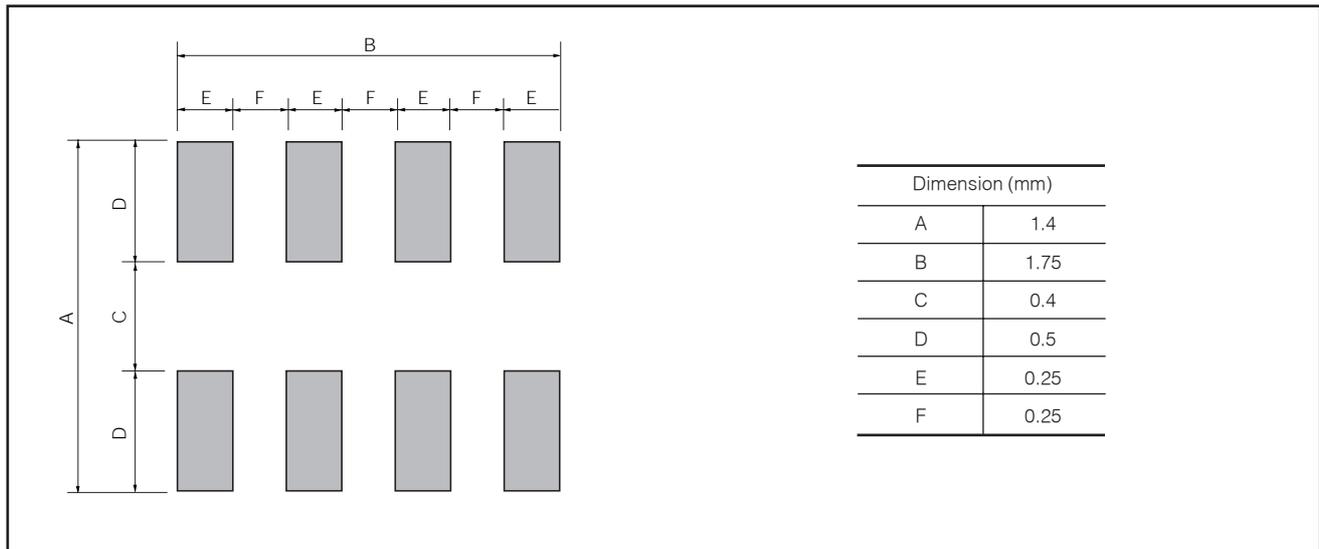
Standard Reel Dimensions (mm)

Part Number	ϕA	ϕB	ϕC	ϕD	E	W	T	t
EXC28B□□□□U	180.0 _{-3.0}	60.0±1.0	13.0±0.5	21.0±0.8	2.0±0.5	9.0±0.3	11.4±1.5	1.2±0.2

Embossed Carrier Dimensions (mm)

Part Number	A	B	W	F	E	P ₁	P ₂	P ₀	ϕD_0	t ₁	t ₂
EXC28B□□□□U	1.20±0.15	2.25±0.15	8.0±0.2	3.5±0.1	1.75±0.10	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1	0.20±0.05	0.9±0.1

Recommended Land Pattern Design

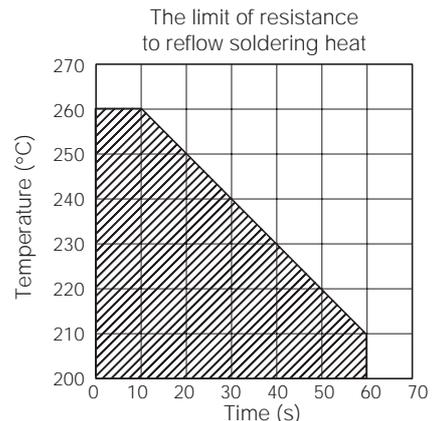
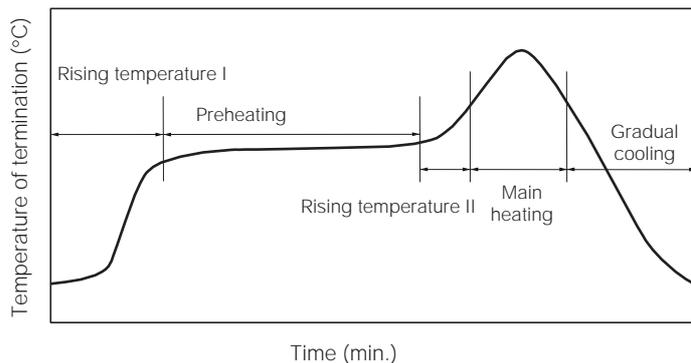


Soldering Conditions

Precautions and recommendations are described below.

- Please contact us for additional information when you using in conditions other than those specified.
- Please measure the temperature of the terminals and evaluate solderability of every type of solder and printed circuit board before actual use.

<Recommended reflow soldering temperature>



Solder	Rising temperature I	Preheating	Rising temperature II	Main heating	Gradual cooling
For solder (Sn-37Pb)	The normal time for preheating 30 s to 60 s	140 °C to 160 °C 60 s to 120 s	Preheating to 200 °C 20 s to 40 s	235±10 °C Peak	200 °C to 100 °C 1 °C to 4 °C/s
For lead-free solder (Sn-3Ag-0.5Cu)	The normal time for preheating 30 s to 60 s	150 °C to 170 °C 60 s to 120 s	Preheating to 210 °C 20 s to 40 s	250±10 °C Peak	210 °C to 100 °C 1 °C to 4 °C/s

* Reflow soldering should be a maximum of two times.

<Repair with hand soldering>

- Use a soldering iron with tip temperature of 280 °C or less. Solder each termination for 3 seconds or less.

⚠ Safety Precautions

1. Flux: Use rosin type or non-halogen type flux.
2. Cleaning agent: Use alcohol based solvent only. Consult with us before using any other type of cleaning agent.
3. Excessive mechanical stress may damage the components. Handle with care.
4. Store under temperature ranging from -5 °C to +40 °C and relative humidity from 40 % to 60%. Avoid rapid changes of temperature and humidity.
5. Use the components within half a year after date of inspection for shipment.
6. Before ordering, test the sample components in your application to ensure proper function and compatibility.